

01-25-1999

U.S. DEPARTMENT OF COMMERCE

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IBM Docket No.:

Ex. Mail #EM28674572



To the Honorable Commissioner of Patents and

100947691

al documents or copy thereof. EN9-96-077

1. Name of conveying party(ies):

Mark Vincent Pierson
Thurston Bryce Youngs, Jr.

Additional names of conveying party(ies) attached?

☐ yes ☒ no

3. Nature of Conveyance

☒ Assignment ☐ Merger
☐ Security Agreement ☐ Change of Name
☐ Other

Execution Date: 12/18/96; 12/20/96

2. Name and address of receiving party(ies):

Name: International Business Machines Corporation

Internal Address:

Street Address: Old Orchard RoadCity: ArmonkState: New YorkZip: 10504Additional name(s) & address(es) attached? ☐ yes ☒ no

4. Application number(s) or patent number(s):

Title: **HIGH DENSITY EDGE MOUNTING OF CHIPS**If this document is being filed together with a new application, the execution date of the application is 12/18/96; 12/20/96

A. Patent Application No(s).

EN996077

B. Patent No(s).

Additional numbers attached? ☐ Yes ☒ No

5. Name and address of party to whom correspondence concerning document should be mailed:

Marshall M. Curtis, Esq.
Whitham, Curtis, Whitham & McGinn
Reston International Center
11800 Sunrise Valley Drive
Suite 900
Reston, Virginia 201916. Total number of applications and patents involved: 1

7. Total fee (37 CVF 3.41):

\$ 40.00☐ Enclosed☒ Authorized to be charged to deposit account☒ Total fee due☐ Any deficiencies in the enclosed fees

8. Deposit account number:

09-0457

CERTIFICATE OF MAILING UNDER 37 CFR 1.10

This certificate is being filed to show that the correspondence is being deposited with the United States Postal Service in an envelope addressed to the Assistant Commissioner for Patents, Washington, D.C. 20231, as "Express Mail Post Office to Addressee"

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9. Statement and signature

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Lawrence R. Fraley

Name of Person Signing

Registration #26,885

Tel.: 607-755-3207

Signature Lawrence R. FraleyDate January 17, 1997Total number of pages including cover sheet: 2

IBM Docket No.:
EN9-95-077**ASSIGNMENT****WHEREAS, we**

- | | | |
|-----|--|---|
| (1) | Mark Vincent Pierson
County of Broome | City of Binghamton
State of New York |
| (2) | Thurston Bryce Youngs, Jr.
County of Broome | City of Vestal
State of New York |

Title have invented certain improvements in
HIGH DENSITY EDGE MOUNTING OF CHIPS

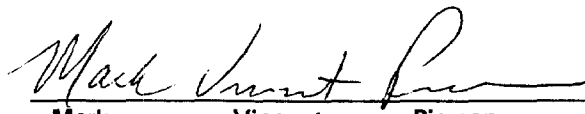
Dates That and have executed, respectively, a United States patent application therefore on
Inventors
Signed the
Declaration

(1) 12/18/ , 1996 (2) 12/20 , 1996

Whereas, INTERNATIONAL BUSINESS MACHINES CORPORATION, a corporation of New York, having a place of business at Armonk, New York 10504, (hereinafter called IBM), desires to acquire the entire right, title and interest in the said application and invention, and to any United States and foreign patents to be obtained therefore;


Now therefore, for a valuable consideration, receipt whereof is hereby acknowledged, we the above named hereby sell, assign, and transfer to IBM, its successors and assigns, the entire right, title and interest in the said application and invention therein disclosed for the United States and foreign countries, and all rights of priority resulting from the filing of said United States application, and we request the Commissioner of Patents to issue any Letters Patent granted upon the invention set forth in said application to IBM, its successors and assigns; and we hereby agree that IBM may apply for foreign Letters Patent on said invention and we will execute all papers necessary in connection with the United States and foreign applications when called upon to do so by IBM.

City (1) Signed at Endicott, NY
Date on 12/18/96


Mark Vincent Pierson
First Name Middle Initial Last Name

signature
inventor

City (2) Signed at ENDICOTT, NY
Date on 12/20/96


Thurston Bryce Youngs, Jr.
First Name Middle Initial Last Name

signature
inventor